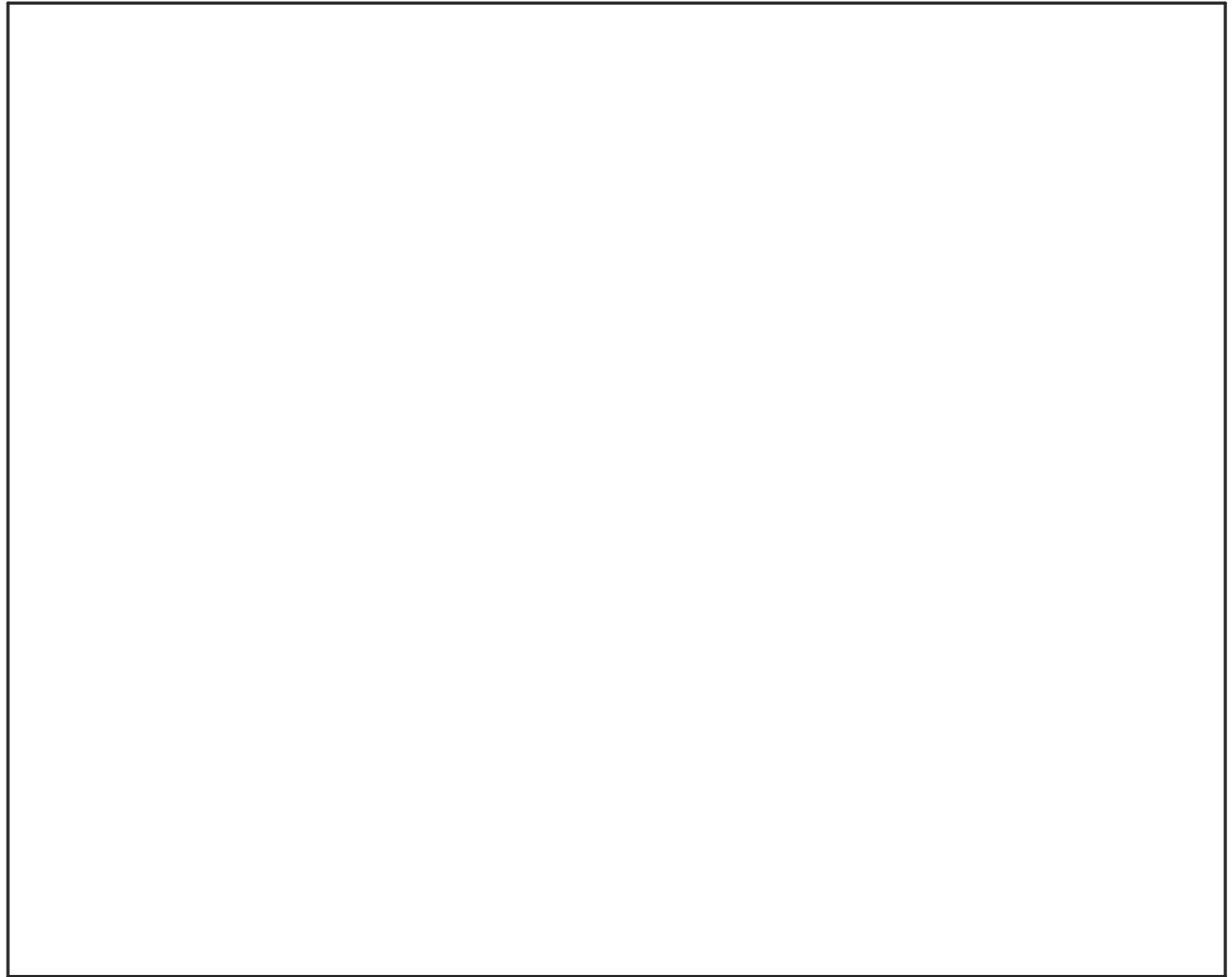


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01375	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01375		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/15/2017 11:39:07 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01375	REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01375		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/15/2017 11:39:08 PM	TEXAS INSTRUMENTS	

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